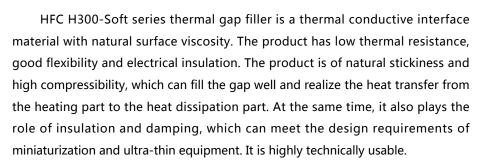
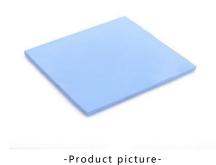
### Innovative Materials Manufacturer

# HFC H300—Soft series

## 【Thermal Gap Filler】

## **DATA SHEET**





### **FEATURES:**

- •Ultra-soft, excellent compression performance
- •Low thermal resistance
- •Being recognized as UL94 V-0
- Viscous surface
- •Being able to work under low pressure
- •Excellent insulation performance and thermal resistance

#### **APPLICATIONS:**

- •Between chip and heat-dissipation modules
- Optoelectronic Industry
- Netcom products
- •New energy battery and vehicles industry
- Household appliances
- Wearable equipments

This series of products are environmentally compliant with RoHS 2.0, halogen, and REACH standards.

**STORAGE CONDITIONS**: Storage in the darkness

STORAGE TEMPERATURE :  $\le 30 \, ^{\circ}\text{C}$ STORAGE HUMIDITY :  $\le 70\%$ 

The height of the stacking should not be more than 7 layers and the total height should not be more than 1m.

#### **SHELF LIFE:**

Under storage conditions: 2 year

PROPERTIES			
Items	Parameter	Unit	Test Method
Color	Sky Blue	-	Visual
Thickness	1~4	mm	ASTM D 374
Hardness	20	Shore 00	ASTM D 2240
Density	3.01	g/cc	ASTM D 792
Tensile Strength	≥0.15	Мра	ASTM D 412
Elongation	≥60	%	ASTM D 412
Compression Ratio	≥40(@50Psi)	%	ASTM D 575
UL Certification	V-0,5V	-	UL94
Operating Temperature	-50~200	°C	IEC 60068-2-14
THERMAL CHARACTERISTIC			
Thermal conductivity	3.0	W/m·K	ASTM D 5470
Thermal resistance	≤0.7(@20psi&1mm)	°Cin²/W	ASTM D 5470
ELECTRICAL PROPERTIES			
Breakdown voltage	≥8	kV /mm	ASTM D 149
Volume resistivity	≥1010	Ω.cm	ASTM D 257
Dielectric constant	≥2	@1MHz	ASTM D 150
Dielectric loss	≤0.1	@1MHz	ASTM D 150
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